

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of

Atty Dkt. 829-615

C# M#

KONISHI et al.

TC/A.U.

1722

Serial No. 10/659,261

Examiner: Davis, Robert B.

Filed: September 11, 2003

Date: January 31, 2005

Title: RESIN MOLDING DIE AND PRODUCTION METHOD FOR SEMICONDUCTOR DEVICES USING THE SAME



Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

RESPONSE/AMENDMENT/LETTER

This is a response/amendment/letter in the above-identified application and includes an attachment which is hereby incorporated by reference and the signature below serves as the signature to the attachment in the absence of any other signature thereon.

☐ **Correspondence Address Indication Form Attached.**

Fees are attached as calculated below:

Total effective claims after amendment **5** minus highest number
previously paid for **20** (at least 20) = 0 x \$50.00 \$0.00 (1202)/\$0.00 (2202) \$

Independent claims after amendment **1** minus highest number
previously paid for **3** (at least 3) = 0 x \$200.00 \$0.00 (1201)/\$0.00 (2201) \$

If proper multiple dependent claims now added for first time, (ignore improper); add
\$360.00 (1051)/\$180.00 (2051) \$

Petition is hereby made to extend the current due date so as to cover the filing date of this
paper and attachment(s)

One Month Extension \$120.00 (1251)/\$60.00 (2251)
Two Month Extensions \$450.00 (1252)/\$225.00 (2252)
Three Month Extensions \$1020.00 (1253)/\$510.00 (2253)
Four Month Extensions \$1590.00 (1254)/\$795.00 (2254) \$ 120.00

Terminal disclaimer enclosed, add \$130.00 (1814)/\$65.00 (2814) \$

☐ Applicant claims "small entity" status. ☐ Statement filed herewith

Rule 56 Information Disclosure Statement Filing Fee \$180.00 (1806) \$

Assignment Recording Fee \$40.00 (8021) \$

Other: \$

TOTAL FEE ENCLOSED \$ 120.00

The Commissioner is hereby authorized to charge any deficiency, or credit any overpayment, in the fee(s) filed, or asserted to be filed, or which should have been filed herewith (or with any paper hereafter filed in this application by this firm) to our Account No. 14-1140. A duplicate copy of this sheet is attached.

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NIXON & VANDERHYE P.C.
By Atty: Joseph A. Rhoa, Reg. No. 37,515

Signature: _____



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KONISHI et al.

Atty. Ref.: 829-615; Confirmation No.

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For: RESIN MOLDING DIE AND PRODUCTION METHOD FOR SEMICONDUCTOR
DEVICES USING THE SAME

* * * * *

January 31, 2005

Commissioner for Patents
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Alexandria, VA 22313-1450

Sir:

AMENDMENT

Responsive to the Official Action dated September 29, 2004 (for which petition is hereby
made for a one month extension of time), please amend the above-identified application as
follows:

02/04/2005 BABRAHA1 00000094 10659261

01 FC:1251

120.00 OP